

MATERIAL DECLARATION



Material Number	CM160808 Series			
Product Line	Chip Inductor			
Compliance Date	January 11, 2013			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Core	Alumina	2.39	Aluminum Oxide	1344-28-1	87.67	54.04	61.28
				Manganese Oxide	1313-13-9	3.44	2.12	
				Crystalline Silica	14808-60-7	3.00	1.85	
				Chromium (III) Oxide	1308-38-9	2.30	1.42	
				Titanium Dioxide	13463-67-7	3.00	1.85	
				Others	-	0.59	0.36	
2	Outer Packaging Resin	Epoxy Resin	0.1	Epoxy Resin	29690-82-2	14.00	0.36	2.94
				Epoxy Resin	25068-38-6	13.00	0.34	
				Silica	14808-82-2	68.00	1.75	
				Others	-	5.00	0.13	
3	Coil / Electrode	Cu plating	1.26	Copper	7440-50-8	100.00	32.50	32.50
4	Electrode base-Plating	Ni Plating	0.0044	Nickel	7440-02-0	100.00	0.11	0.11
5	Electrode Plating	Sn Plating	0.1226	Tin	7440-31-5	100.00	3.16	3.16
		Total weight	3.877					

This Document was updated on: 2013/1/11

Important remarks: It is the responsibility of the user to verify they are accessing the latest version.